Electronic Pate	nt App	lication Fee	Transm	ittal			
Application Number:	10	10593137					
Filing Date:	18-	18-Sep-2006					
Title of Invention:	Re:	Resin Composition and Semiconductor Device Produced By Using the Sam					
First Named Inventor/Applicant Name:	Hik	Hikaru Okubo					
Filer:	The	Thomas G. Wiseman/Barbara Helton					
Attorney Docket Number:	03:	033036.110					
Filed as Large Entity	•						
U.S. National Stage under 35 USC 371 Fil	ing Fee	s					
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:					,		
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Extension-of-Time:							
Extension - 1 month with \$0 paid		1251	1	130	130		

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			130